

PCN Number: 20191212000.1		PCN Date: Dec 18 2019	
Title: Qualification of TIPI as an additional AT site for Select Devices			
Customer Contact: PCN Manager		Dept: Quality Services	
Proposed 1st Ship Date: Mar 17 2020		Estimated Sample Availability: Date provided at sample request	
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Texas Instruments is pleased to announce the qualification of TIPI as an additional assembly site for the list of devices below. There are no construction differences between the current and new site.			
Reason for Change:			
Continuity of Supply			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Anticipated impact on Material Declaration			
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp
Changes to product identification resulting from this PCN:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TITL	TAI	TWN	Chung Ho, New Taipei City
TIPI	PHI	PHL	Baguio City
Sample product shipping label (not actual product label)			
<p> TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20 MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 </p> <p> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS </p>			
Product Affected:			
MSP430FR2153TPT	MSP430FR2155TPT	MSP430FR2353TPT	MSP430FR2355TPT
MSP430FR2153TPTR	MSP430FR2155TPTR	MSP430FR2353TPTR	MSP430FR2355TPTR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device #1: MSP430FR2355TPT	QBS Device #2: MSP430FR6989IPZ
AC	Autoclave 121C	96 Hours	QBS #2	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	QBS #2	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	QBS #2	3/231/0
TC	Temperature Cycle, -55/125C	700 Cycles	QBS #2	3/231/0
WBP	Bond Pull	Wires	1/76/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	3/228/0

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL3-260C: MSP430FR2355TPT
- Preconditioning was performed for Autoclave, Biased HAST, Temperature Cycle, and High Temp. Storage Bake.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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